



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 20411

Generic Copy

Issue Date: 17-Apr-2014**TITLE:** Qualification of ON Semiconductor Pocatello (wafer fab) in SOT143 device CM1223-02SR.**PROPOSED FIRST SHIP DATE:** 17-Jul-2014**AFFECTED CHANGE CATEGORY(S):** Die layout & wafer fab site**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or <norhayati.othman@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or <laura.rivers@onsemi.com>

NOTIFICATION TYPE:

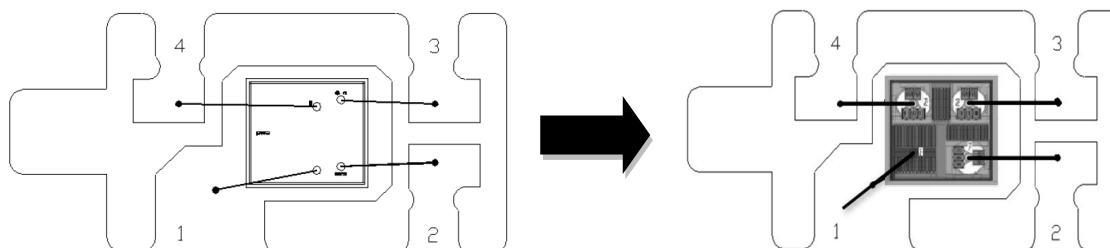
Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This is the final notification announcing that for CM1223-02SR, the wafer fab will be transferred to On Semiconductor Pocatello in Idaho, USA. This fab site is ON Semiconductor's internal factories and certified for ISO/TS 16949. This product will continue to meet RoHS requirement and also Halide Free.

Die layout change:

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 20411****RELIABILITY DATA SUMMARY:****Reliability Test Results:**

Test	Conditions	Interval	Results
HTRB	TA=150C, 80% Rated Voltage	1008 hrs	0/234
TC+PC	TA=-65C to 150C	1000 cyc	0/234
AC+PC	TA=121C RH=100% ~ 15psig	96 hrs	0/234
HAST+PC	TA=130C RH=85% ~ 18.8psig	96 hrs	0/234

ELECTRICAL CHARACTERISTIC SUMMARY:

Available upon request

CHANGED PART IDENTIFICATION:

Product listed in this PCN with Finished Good date codes representing WW28, 2014 or later will be sourced from ON Semiconductor Pocatello.

List of affected General Parts:

CM1223-02SR